

November 2013

# FGA60N60UFD 600 V, 60 A Field Stop IGBT

#### **Features**

- · High Current Capability
- Low Saturation Voltage: V<sub>CE(sat)</sub> = 1.9 V @ I<sub>C</sub> = 60 A
- High Input Impedance
- Fast Switching
- RoHS Compliant

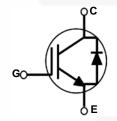
### **Applications**

• Solar Inverter, UPS, Welder, PFC

### **General Description**

Using novel field stop IGBT technology, Fairchild's field stop IGBTs offer the optimum performance for solar inverter, UPS, welder and PFC applications where low conduction and switching losses are essential.





## **Absolute Maximum Ratings**

Symbol	Description		Ratings	Unit	
V <sub>CES</sub>	Collector to Emitter Voltage		600	V	
V <sub>GES</sub>	Gate to Emitter Voltage		± 20	V	
I <sub>C</sub>	Collector Current	$^{\circ}$ T <sub>C</sub> = 25 $^{\circ}$ C	120	А	
'C	Collector Current	$@ T_C = 100^{\circ}C$	60	A	
I <sub>CM (1)</sub>	Pulsed Collector Current	@ $T_C = 25^{\circ}C$	180	A	
P <sub>D</sub>	Maximum Power Dissipation	@ $T_C = 25^{\circ}C$	298	W	
	Maximum Power Dissipation	$@ T_C = 100^{\circ}C$	119	W	
T <sub>J</sub>	Operating Junction Temperature		-55 to +150	°C	
T <sub>stg</sub>	Storage Temperature Range		-55 to +150	°C	
TL	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds		300	°C	

Notes:
1: Repetitive test , Pulse width limited by max. junction temperature

#### **Thermal Characteristics**

Symbol	Parameter	Тур.	Max.	Unit
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction to Case	-	0.33	°C/W
$R_{\theta JC}(Diode)$	Thermal Resistance, Junction to Case	-	1.1	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient		40	°C/W

# **Package Marking and Ordering Information**

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FGA60N60UFDTU	FGA60N60UFD	TO-3P	Tube	N/A	N/A	30

# Electrical Characteristics of the IGBT $T_C = 25$ °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	teristics					
BV <sub>CES</sub>	Collector to Emitter Breakdown Voltage	$V_{GE} = 0 \text{ V}, I_{C} = 250 \mu\text{A}$	600	-	-	V
$\Delta BV_{CES} \ \Delta T_J$	Temperature Coefficient of Breakdown Voltage	$V_{GE} = 0 \text{ V, } I_{C} = 250 \mu\text{A}$	-	0.67	-	V/°C
T <sub>CES</sub>	Collector Cut-Off Current	V <sub>CE</sub> = V <sub>CES</sub> , V <sub>GE</sub> = 0 V	-	-	250	μА
I <sub>GES</sub>	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0 V$	-	-	±400	nA
On Charac	teristics					
V <sub>GE(th)</sub>	G-E Threshold Voltage	$I_C = 250 \mu A, V_{CE} = V_{GE}$	4.0	5.0	6.5	V
GE(III)		I <sub>C</sub> = 60 A, V <sub>GE</sub> = 15 V	_	1.9	2.4	V
V <sub>CE(sat)</sub>	Collector to Emitter Saturation Voltage	I <sub>C</sub> = 60 A, V <sub>GE</sub> = 15 V, T <sub>C</sub> = 125°C	-	2.1	-	V
Dynamic C	haracteristics				1	
C <sub>ies</sub>	Input Capacitance		-	2855	-	pF
C <sub>oes</sub>	Output Capacitance	$V_{CE} = 30 \text{ V}, V_{GE} = 0 \text{ V},$ f = 1  MHz	-	325	-	pF
C <sub>res</sub>	Reverse Transfer Capacitance	1 - 1 1011 12	-	110	-	pF
Switching	Characteristics					
t <sub>d(on)</sub>	Turn-On Delay Time		-	23	-	ns
t <sub>r</sub>	Rise Time		-	58	-	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{CC} = 400 \text{ V}, I_{C} = 60 \text{ A},$	-	130	-	ns
t <sub>f</sub>	Fall Time	$R_G = 5 \Omega$ , $V_{GE} = 15 V$ ,	-	40	80	ns
E <sub>on</sub>	Turn-On Switching Loss	Inductive Load, T <sub>C</sub> = 25°C	-	1.81	-	mJ
E <sub>off</sub>	Turn-Off Switching Loss		-	0.81	-	mJ
E <sub>ts</sub>	Total Switching Loss		-	2.62	-	mJ
t <sub>d(on)</sub>	Turn-On Delay Time		_	22	- /	ns
t <sub>r</sub>	Rise Time		-	61	- /	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{CC} = 400 \text{ V}, I_{C} = 60 \text{ A},$	-	141	-	ns
t <sub>f</sub>	Fall Time	$R_G = 5 \Omega$ , $V_{GE} = 15 V$ ,	-	63	-	ns
E <sub>on</sub>	Turn-On Switching Loss	Inductive Load, T <sub>C</sub> = 125°C	-	1.92	- /	mJ
E <sub>off</sub>	Turn-Off Switching Loss		-	1.23	- (	mJ
E <sub>ts</sub>	Total Switching Loss		-	3.15	- \	mJ
Qg	Total Gate Charge		-	188	-	nC
Q <sub>ge</sub>	Gate to Emitter Charge	$V_{CE} = 400 \text{ V}, I_{C} = 60 \text{ A},$ $V_{GF} = 15 \text{ V}$	-	21	-	nC
Q <sub>gc</sub>	Gate to Collector Charge	▼GE = 10 V	-	97	-	nC

# Electrical Characteristics of the Diode $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions		Min.	Тур.	Max	Unit
V <sub>FM</sub>	Diode Forward Voltage	I <sub>F</sub> = 30 A	$T_{\rm C} = 25^{\rm o}{\rm C}$	=	2.0	2.6	V
	Diodo i ornara voltago	- 00 /\	$T_{\rm C} = 125^{\rm o}{\rm C}$	<sub>C</sub> = 125°C -	1.8	-	
	Diode Reverse Recovery Time		$T_{\rm C} = 25^{\rm o}{\rm C}$	-	47	-	ns
	2.000 1.010.00 1.00010., 1	$I_F = 30 \text{ A}, \text{ di}_F/\text{dt} = 200 \text{ A}/\mu\text{s}$	$T_{\rm C} = 125^{\rm o}{\rm C}$	-	179	-	
	Diode Reverse Recovery Charge	ης = 00 / ι, αις/αι = 200 / ι μο	$T_C = 25^{\circ}C$	-	83	-	nC
			$T_{\rm C} = 125^{\rm o}{\rm C}$	-	567	-	

Figure 1. Typical Output Characteristics

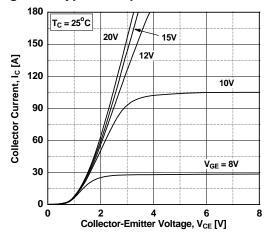


Figure 3. Typical Saturation Voltage Characteristics

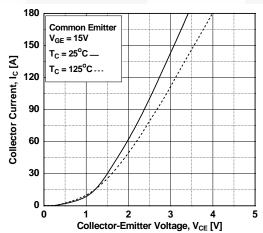
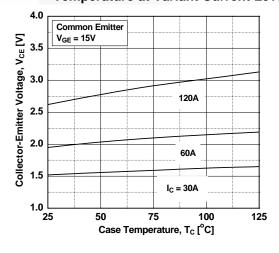
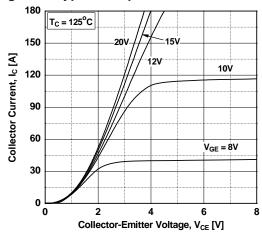


Figure 5. Saturation Voltage vs. Case
Temperature at Variant Current Level



**Figure 2. Typical Output Characteristics** 



**Figure 4. Transfer Characteristics** 

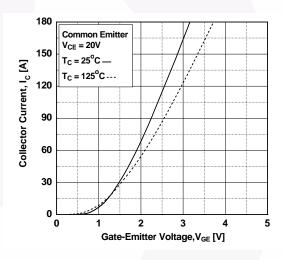


Figure 6. Saturation Voltage vs. V<sub>GE</sub>

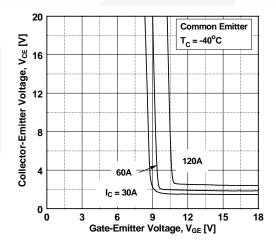


Figure 7. Saturation Voltage vs. V<sub>GE</sub>

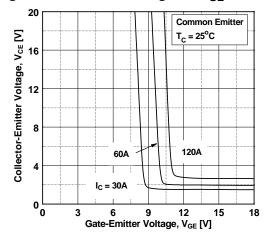


Figure 8. Saturation Voltage vs. V<sub>GE</sub>

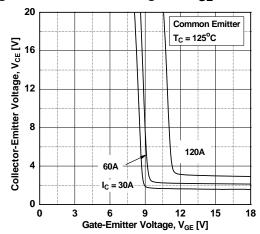


Figure 9. Capacitance Characteristics

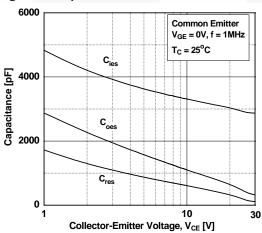


Figure 10. Gate charge Characteristics

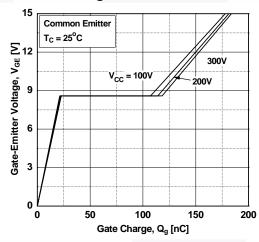


Figure 11. SOA Characteristics

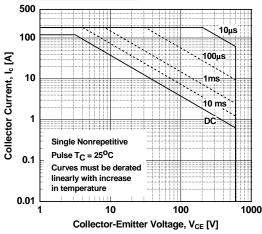


Figure 12. Turn off Switching SOA Characteristics

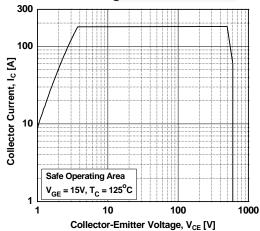


Figure 13. Turn-on Characteristics vs. **Gate Resistance** 

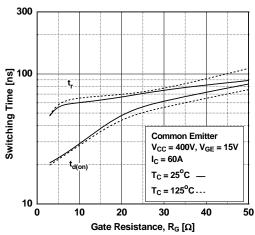


Figure 15. Turn-on Characteristics vs.

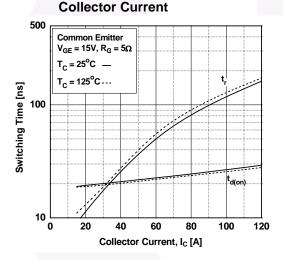


Figure 17. Switching Loss vs. Gate Resistance

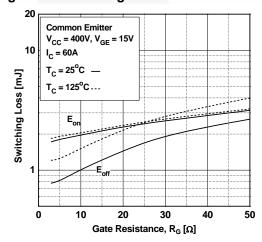


Figure 14. Turn-off Characteristics vs. **Gate Resistance** 

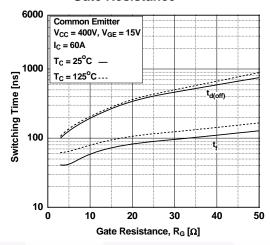


Figure 16. Turn-off Characteristics vs. **Collector Current** 

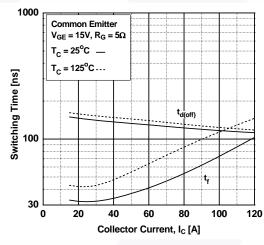


Figure 18. Switching Loss vs. Collector Current

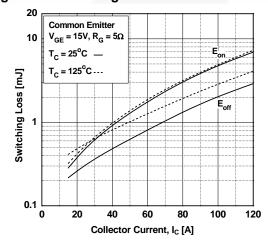


Figure 19. Forward Characteristics

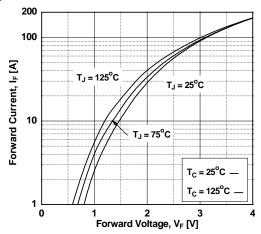


Figure 20. Reverse Current

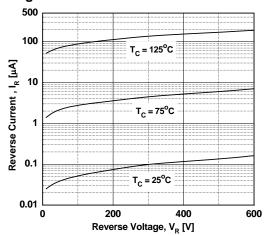


Figure 21. Stored Charge

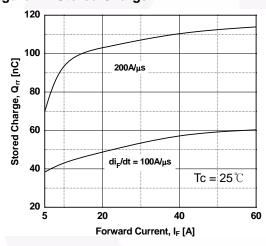


Figure 22. Reverse Recovery Time

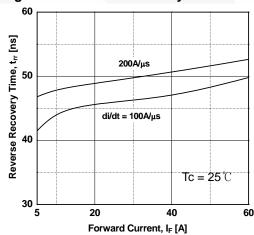
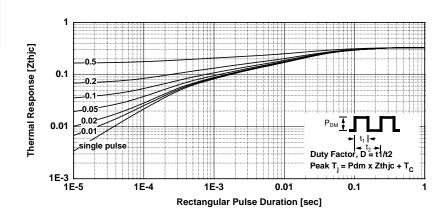


Figure 23. Transient Thermal Impedance of IGBT



#### **Mechanical Dimensions** 5.00 4.60 13.80 15.80 13.40 1.65 $\phi_{3.10}^{3.30}$ 15.40 5.20 1.45 4.80 (R0.50) 16.96 20.10 18.90 16.56 ø<sup>7.20</sup> 19.70 18.50 6.80 3 3.70 ( 1.85 ) 3.30 20.30 2.20 2.90 19.70 1.90 1.80 3.20 2.80 1.20 0.80 $\oplus | \emptyset 0.55 (M)$ 0.75 0.55 5.45 5.45 NOTES: UNLESS OTHERWISE SPECIFIED A) THIS PACKAGE CONFORMS TO EIAJ SC-65 PACKAGING STANDARD. ALL DIMENSIONS ARE IN MILLIMETERS. (R0.50) DIMENSION AND TOLERANCING PER D) DIMENSIONS ARE EXCLUSSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSSIONS. E) THIS PACKAGE IS INTENDED ONLY FOR TO3PN. F) DRAWING FILE NAME: TO3P03AREV4.

Figure 24. TO-3P 3L - 3LD, T03, PLASTIC, EIAJ SC-65

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Dimensions in Millimeters





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Datasheet Identification Product Status		Definition			
Advance Information Formative / In Design		Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.			
Preliminary First Production		Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.			
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